

In the claims:

Claim 1 (currently amended) A tin-silver based lead-free solder, containing 0.3 to 1% by weight of zinc (Zn) added to a solder, consisting of ~~comprising~~ a tin-silver system containing no lead.

Claim 2 (currently amended) ~~The~~ A tin-silver based lead-free solder ~~of claim 1,~~ containing 0.3 to 1% of zinc further containing indium (In) added thereto.

Cancel **Claim 3**.

Claim 4 (currently amended) The tin-silver based lead-free solder of claim 2, containing less than 10% by weight of indium (In) and 0.1 to 1.0% by weight of zinc (Zn) and the remainder is tin and silver.

Claim 5 (previously presented) A joint structure, comprising bodies to be joined are joined together by the tin-silver based lead-free solder of claim 1.

Claim 6 (previously presented) The joint structure of claim 5, wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

Claim 7 (currently amended) The joint structure of claim 6, wherein said ~~electroless~~ ~~plating~~ layer is a Ni-Pplating.

Please add the following claims:

Claim 8 (new) A solder of claim 1 containing 3.5% by weight of silver.

Claim 9 (new) A solder of claim 2 containing 3.5% by weight of silver.

Claim 10 (new) A solder of claim 2 wherein the amount of indium is at least 8% by weight.

Claim 11 (new) A joint structure, comprising bodies to be joined are joined together by the tin-silver based lead-free solder of claim 2.

Claim 12 (new) The joint structure of claim 5 wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

Claim 13 (new) The joint structure of claim 11 wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

Claim 14 (new) The joint structure of claim 11 wherein an electroless plating layer is provided on surfaces of said bodies to be joined.

Claim 15 (new) The joint structure of claim 12 wherein said electrodes plating layer is a Ni-P plating.

Claim 16 (new) The joint structure of claim 11 wherein said electrodes plating layer is a Ni-P plating.